

# 1.5V Drive Pch MOSFET

## RAL035P01

### ● Structure

Silicon P-channel MOSFET

### ● Features

- 1) Low On-resistance.
- 2) Small high power package.
- 3) Low voltage drive.(1.5V)

### ● Application

Switching

### ● Packaging specifications

| Type      | Package                      | Taping |
|-----------|------------------------------|--------|
|           | Code                         | TCR    |
|           | Basic ordering unit (pieces) | 3000   |
| RAL035P01 |                              | ○      |

### ● Absolute maximum ratings (Ta = 25°C)

| Parameter                      |            | Symbol      | Limits      | Unit |
|--------------------------------|------------|-------------|-------------|------|
| Drain-source voltage           |            | $V_{DSS}$   | -12         | V    |
| Gate-source voltage            |            | $V_{GSS}$   | 0 to -8     | V    |
| Drain current                  | Continuous | $I_D$       | ±3.5        | A    |
|                                | Pulsed     | $I_{DP}$ *1 | ±12         | A    |
| Source current<br>(Body Diode) | Continuous | $I_S$       | -0.8        | A    |
|                                | Pulsed     | $I_{SP}$ *1 | -12         | A    |
| Power dissipation              |            | $P_D$ *2    | 1           | W    |
| Channel temperature            |            | $T_{ch}$    | 150         | °C   |
| Range of storage temperature   |            | $T_{stg}$   | -55 to +150 | °C   |

 \*1  $P_w \leq 10\mu s$ , Duty cycle  $\leq 1\%$ 

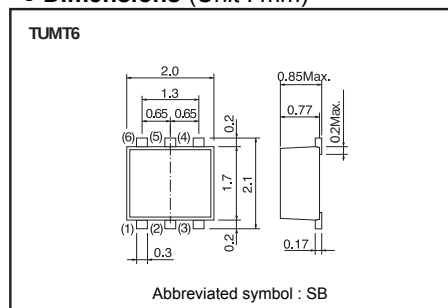
\*2 Mounted on a ceramic board.

### ● Thermal resistance

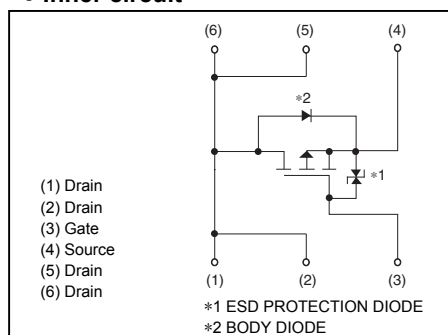
| Parameter          | Symbol           | Limits | Unit   |
|--------------------|------------------|--------|--------|
| Channel to Ambient | $R_{th}(ch-a)^*$ | 125    | °C / W |

\*Mounted on a ceramic board.

### ● Dimensions (Unit : mm)



### ● Inner circuit



## ● Electrical characteristics (Ta = 25°C)

| Parameter                               | Symbol         | Min. | Typ. | Max. | Unit       | Conditions                    |
|-----------------------------------------|----------------|------|------|------|------------|-------------------------------|
| Gate-source leakage                     | $I_{GSS}$      | -    | -    | -10  | $\mu A$    | $V_{GS} = -8V, V_{DS} = 0V$   |
| Drain-source breakdown voltage          | $V_{(BR)DSS}$  | -12  | -    | -    | V          | $I_D = -1mA, V_{GS} = 0V$     |
| Zero gate voltage drain current         | $I_{DSS}$      | -    | -    | -10  | $\mu A$    | $V_{DS} = -12V, V_{GS} = 0V$  |
| Gate threshold voltage                  | $V_{GS(th)}$   | -0.3 | -    | -1.0 | V          | $V_{DS} = -6V, I_D = -1mA$    |
| Static drain-source on-state resistance | $R_{DS(on)}^*$ | -    | 30   | 42   | m $\Omega$ | $I_D = -3.5A, V_{GS} = -4.5V$ |
|                                         |                | -    | 40   | 56   |            | $I_D = -1.7A, V_{GS} = -2.5V$ |
|                                         |                | -    | 55   | 82   |            | $I_D = -1.7A, V_{GS} = -1.8V$ |
|                                         |                | -    | 75   | 150  |            | $I_D = -0.7A, V_{GS} = -1.5V$ |
| Forward transfer admittance             | $ Y_{fs} ^*$   | 4    | -    | -    | S          | $I_D = -3.5A, V_{DS} = -6V$   |
| Input capacitance                       | $C_{iss}$      | -    | 2700 | -    | pF         | $V_{DS} = -6V$                |
| Output capacitance                      | $C_{oss}$      | -    | 170  | -    | pF         | $V_{GS} = 0V$                 |
| Reverse transfer capacitance            | $C_{rss}$      | -    | 150  | -    | pF         | $f = 1MHz$                    |
| Turn-on delay time                      | $t_{d(on)}^*$  | -    | 10   | -    | ns         | $I_D = -1.7A, V_{DD} = -6V$   |
| Rise time                               | $t_r^*$        | -    | 30   | -    | ns         | $V_{GS} = -4.5V$              |
| Turn-off delay time                     | $t_{d(off)}^*$ | -    | 230  | -    | ns         | $R_L = 3.5\Omega$             |
| Fall time                               | $t_f^*$        | -    | 75   | -    | ns         | $R_G = 10\Omega$              |
| Total gate charge                       | $Q_g^*$        | -    | 22   | -    | nC         | $I_D = -3.5A$                 |
| Gate-source charge                      | $Q_{gs}^*$     | -    | 3.9  | -    | nC         | $V_{DD} = -6V$                |
| Gate-drain charge                       | $Q_{gd}^*$     | -    | 3.1  | -    | nC         | $V_{GS} = -4.5V$              |

\*Pulsed

## ● Body diode characteristics (Source-Drain) (Ta = 25°C)

| Parameter       | Symbol     | Min. | Typ. | Max. | Unit | Conditions                 |
|-----------------|------------|------|------|------|------|----------------------------|
| Forward Voltage | $V_{SD}^*$ | -    | -    | -1.2 | V    | $I_s = -3.5A, V_{GS} = 0V$ |

\*Pulsed

●Electrical characteristic curves (Ta=25°C)

Fig.1 Typical Output Characteristics( I )

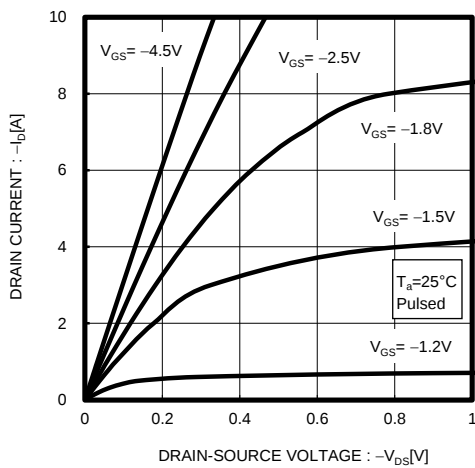


Fig.2 Typical Output Characteristics( II )

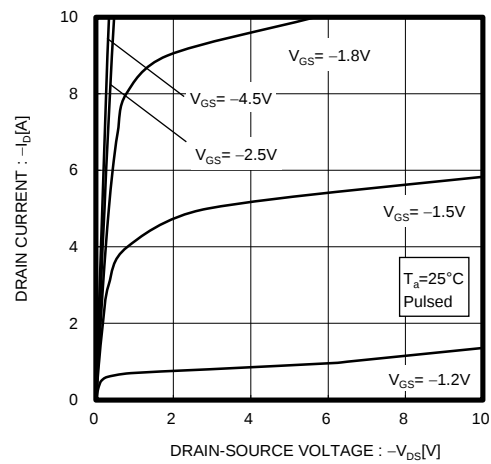


Fig.3 Typical Transfer Characteristics

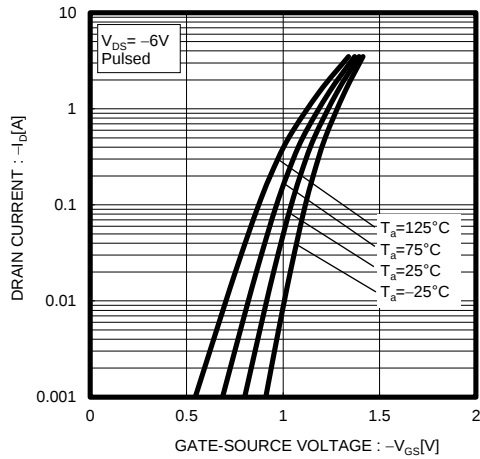


Fig.4 Static Drain-Source On-State Resistance vs. Drain Current( I )

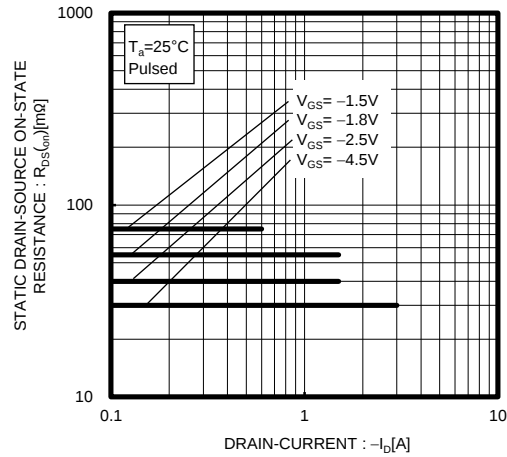


Fig.5 Static Drain-Source On-State Resistance vs. Drain Current( II )

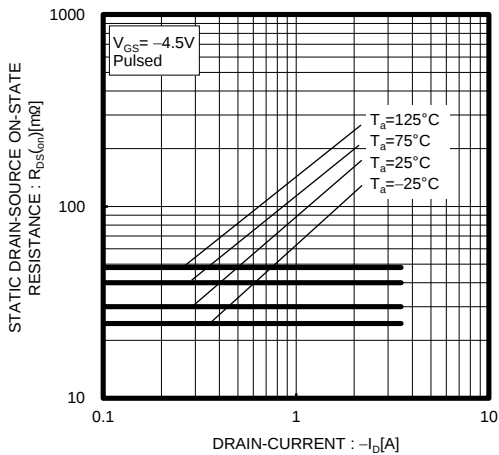


Fig.6 Static Drain-Source On-State Resistance vs. Drain Current( II )

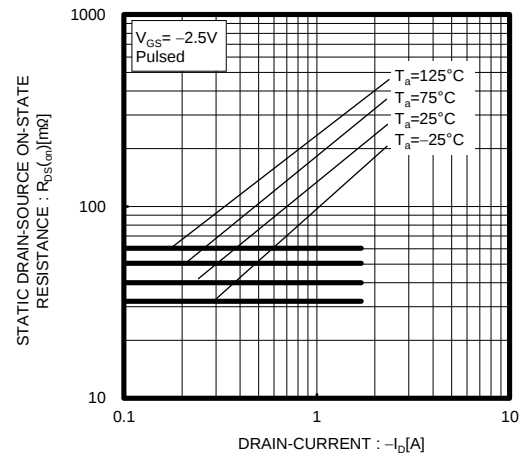


Fig.7 Static Drain-Source On-State Resistance vs. Drain Current(III)

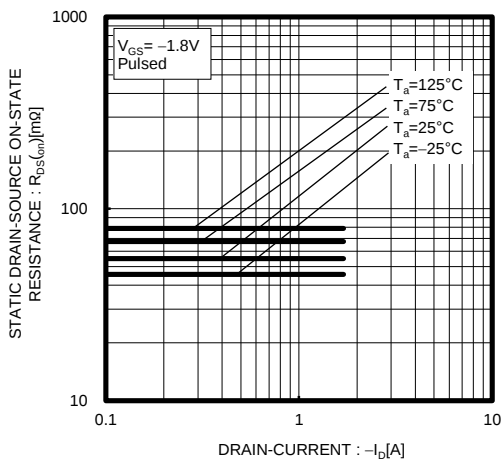


Fig.8 Static Drain-Source On-State Resistance vs. Drain Current(IV)

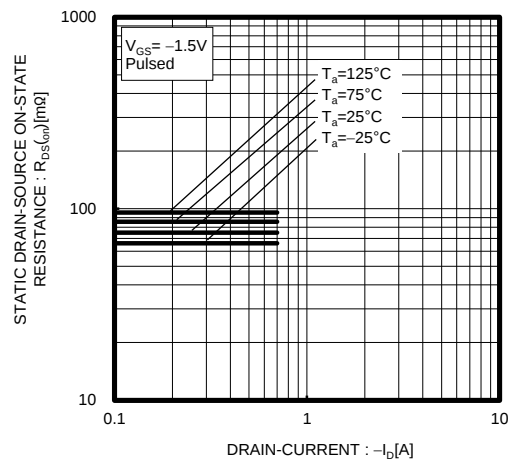


Fig.9 Forward Transfer Admittance vs. Drain Current

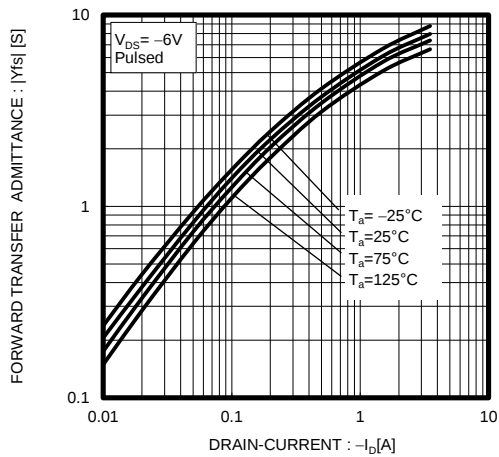


Fig.10 Reverse Drain Current vs. Source-Drain Voltage

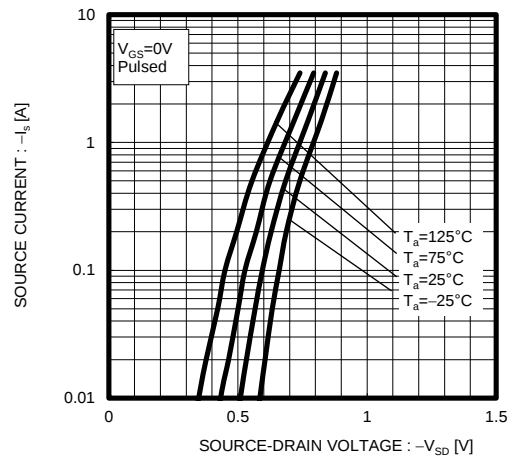


Fig.11 Static Drain-Source On-State Resistance vs. Gate Source Voltage

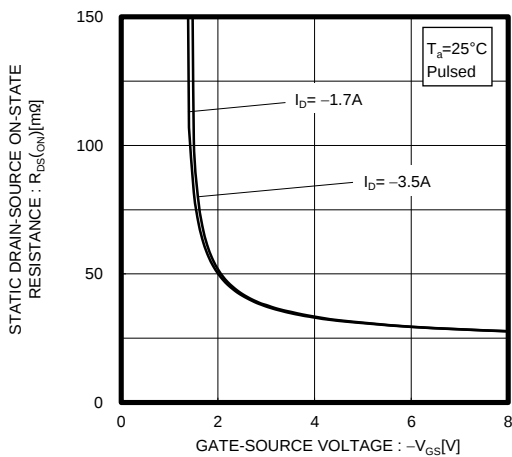


Fig.12 Switching Characteristics

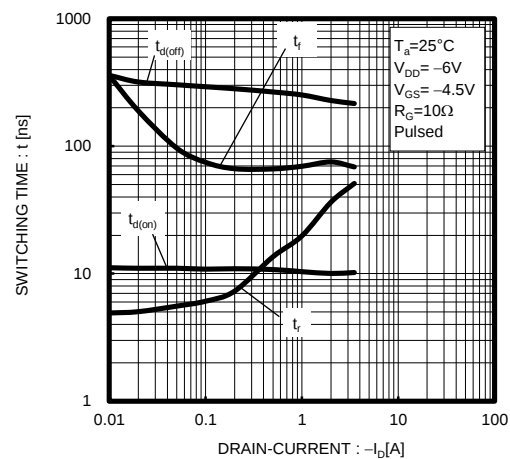


Fig.13 Dynamic Input Characteristics

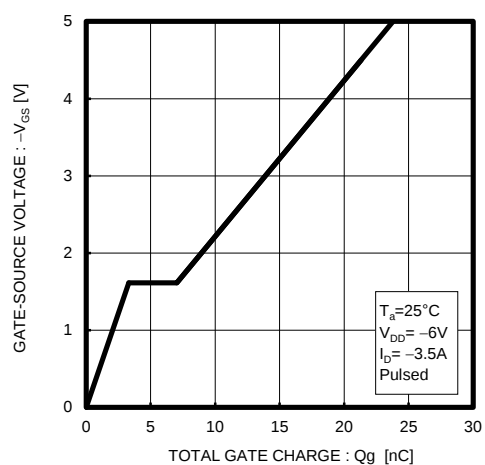
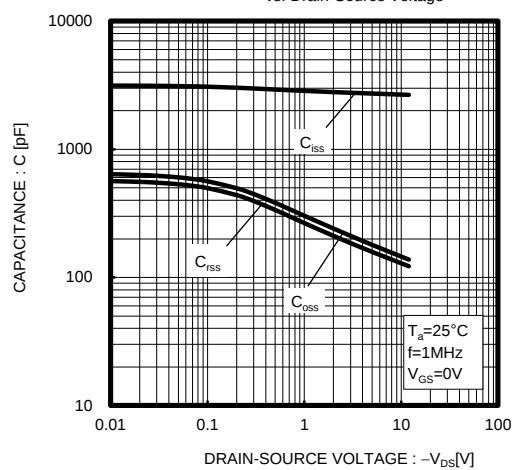


Fig.14 Typical Capacitance vs. Drain-Source Voltage



### ● Measurement circuits

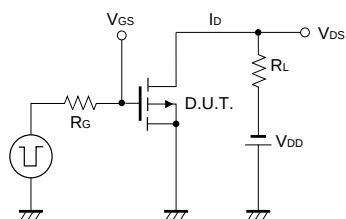


Fig.1-1 Switching Time Measurement Circuit

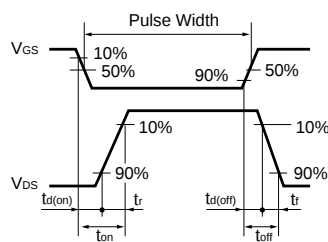


Fig.1-2 Switching Waveforms

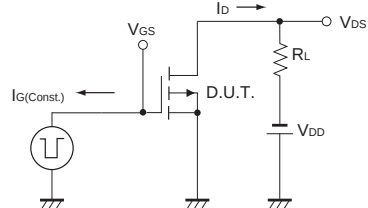


Fig.2-1 Gate Charge Measurement Circuit

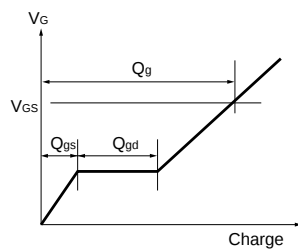


Fig.2-2 Gate Charge Waveform

### ● Notice

This product might cause chip aging and breakdown under the large electrified environment. Please consider to design E: protection circuit.

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